

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	15APR22	R. WHITNEY
B	CHANGES AS PER ECR-109621	04OCT22	R. WHITNEY
C	CHANGES AS PER ECR-111941	27JAN23	R. WHITNEY
D	CHANGES AS PER ECR-113566	11APR23	R. WHITNEY
E	CHANGES AS PER ECR-115079	08AUG23	R. WHITNEY

ASSEMBLY NOTES:

1. BOARD ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00119 (LATEST REVISION).
2. REPAIRS PER IPC-7711/21(LATEST REVISION) ARE ALLOWED.
3. REPAIRS ARE NOT ALLOWED IN SOLDERMASK FREE AREAS ON EITHER SIDE OF THE BOARD.
4. SEE DETAIL A FOR Y1 INSTALLATION.
5. U9 IS A DEVICE-SOCKET COMBO AND FOLLOWS THIS SOLDERPASTE INSTRUCTION:

SUPPLIED PART	INSTALLED PART	PASTEMASK
U20(SOCKET)	INSTALLED SOCKET	NO PASTEMASK
U20(DEVICE)	INSTALLED DUT	PASTEMASK
6. RoHS COMPLIANCE: ASSEMBLY VENDOR SHOULD ASSURE COMPLIANCE WITH LEAD-FREE AND RoHS PCB ASSEMBLY STANDARDS (EU RoHS DIRECTIVE 2002/95/EC).
7. BOARD ASSEMBLY SPECIAL NOTES: (IN ORDER TO MINIMIZE MIC DEVICES (U11-U14) DAMAGE)

A. DO NOT BOARD WASH OR CLEAN AFTER THE REFLOW PROCESS.

B. DO NOT BRUSH BOARD WITH OR WITHOUT SOLVENTS AFTER THE REFLOW PROCESS.

C. DO NOT DIRECTLY EXPOSE TO ULTRASONIC PROCESSING, WELDING, OR CLEANING.

D. DO NOT INSERT ANY OBJECT IN PORT HOLE OF DEVICE AT ANY TIME.

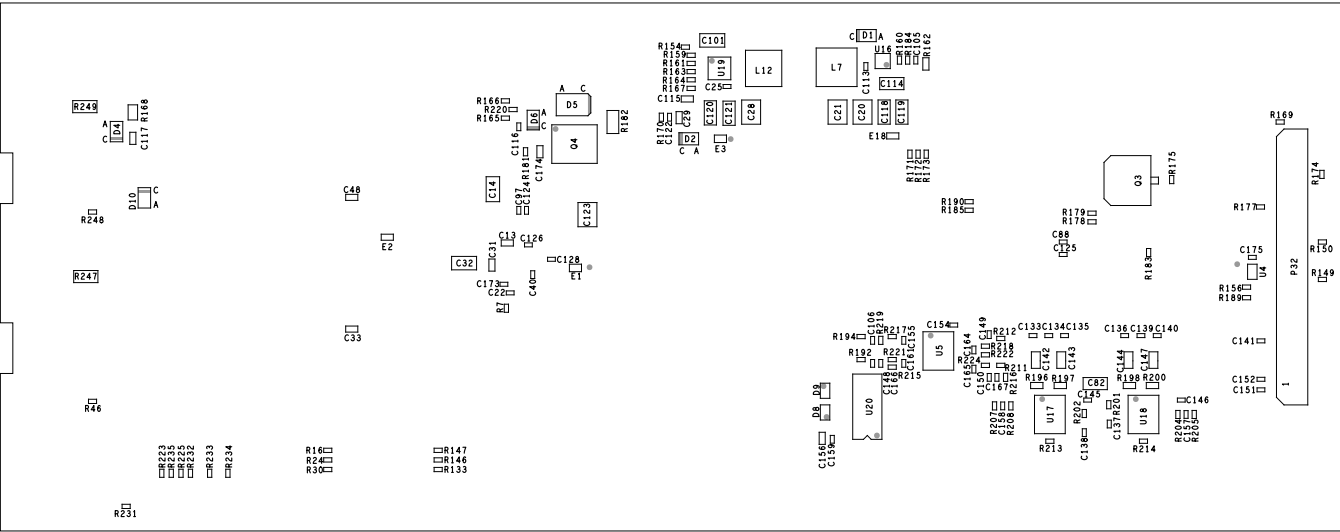
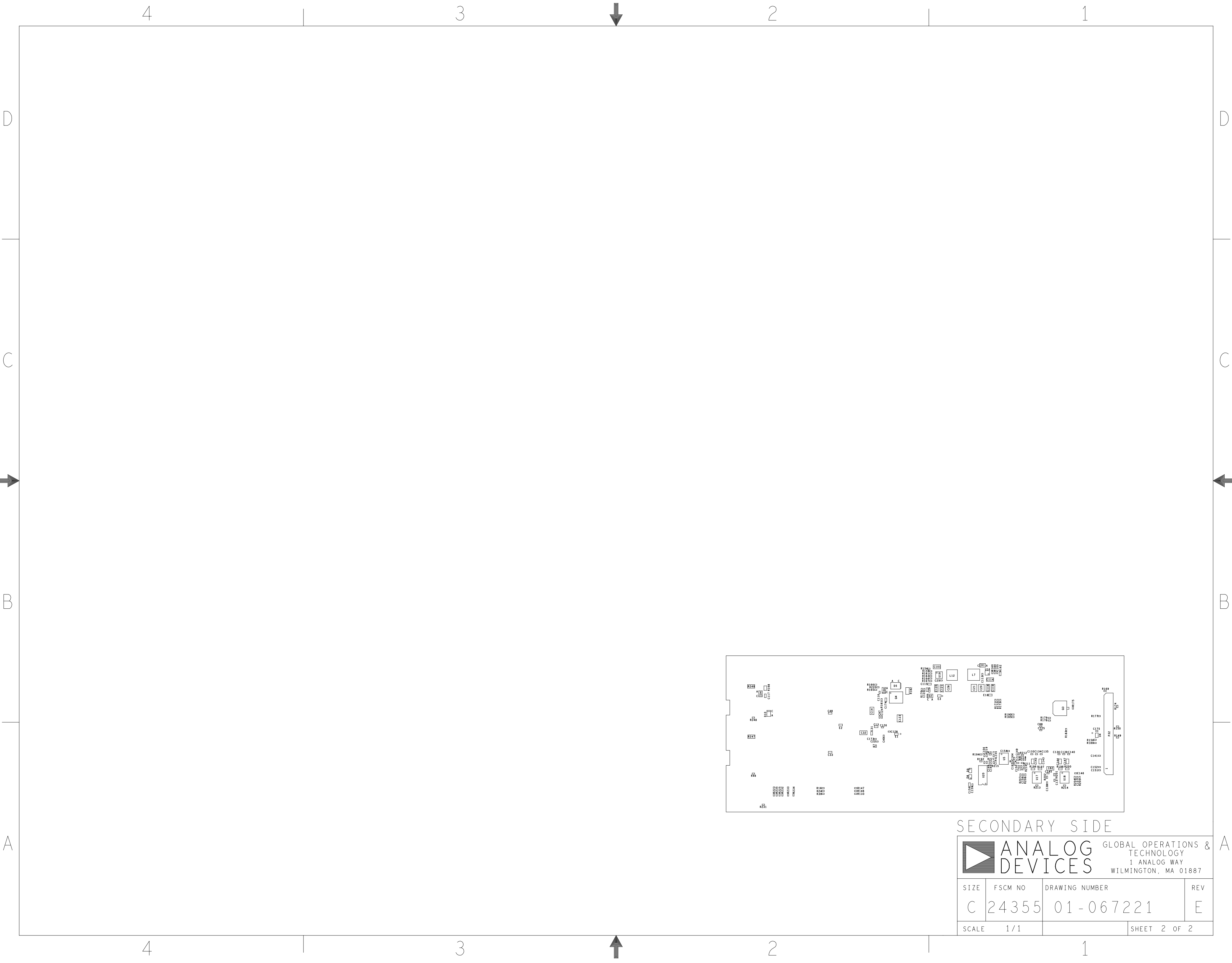
E. DO NOT APPLY OVER 30 PSI OF AIR PRESSURE INTO THE PORT HOLE.

F. DO NOT PULL A VACUUM OVER PORT HOLE OF THE MICROPHONE.

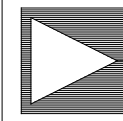
G. DO NOT APPLY A VACUUM WHEN REPACKING INTO SEALED BAGS AT A RATE FASTER THAN 0.5 ATM/SEC.
8. BOARDS TO BE SHIPPED SINGULATED AFTER ASSEMBLY PROCESS. SMOOTHEN EDGES AND FREE FROM BURRS AFTER DEPANELIZATION PROCESS.

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS ANGLES .XX -.010 --1/32 -- 2 .XXX -.005 .XXXX -.0050	APPROVAL	DATE	<div><div></div><div>ANALOG DEVICES</div></div> <div>GLOBAL OPERATIONS & TECHNOLOGY 1 ANALOG WAY WILMINGTON, MA 01887</div>			
	TEMPLATE ENGINEER					
MATERIAL	HARDWARE SERVICES M. VALE	03NOV21	TITLE ASSEMBLY EVAL-AD2437A1MZ_BRD CUSTOMER EVALUATION Z			
	HARDWARE SYSTEMS					
	TEST ENGINEER					
	COMPONENT ENGINEER M. YAN	03NOV21				
FINISH	TEST PROCESS		SIZE C	FSCM NO 24355	DRAWING NUMBER 01-067221	REV E
	HARDWARE RELEASE K. JABATAN	03NOV21				
	DESIGNER R. PLANADA	15APR22				
DO NOT SCALE DWG	PTD ENGINEER R. WHITNEY	15APR22	SCALE 1/1			SHEET 1 OF 2
	CHECKER					



SECONDARY SIDE

ANALOG
DEVICES

GLOBAL OPERATIONS &
TECHNOLOGY
1 ANALOG WAY
WILMINGTON, MA 01887

SIZE	FSCM NO	DRAWING NUMBER	REV
C	24355	01-067221	E
SCALE	1 / 1	SHEET 2 OF 2	